

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Shohei Hata</td> <td>12/03/2008</td> </tr> <tr> <td>Eiji Sakamoto</td> <td>12/03/2008</td> </tr> <tr> <td>Naoki Matsushima</td> <td>12/04/2008</td> </tr> <tr> <td>Hideaki Takemori</td> <td>12/08/2008</td> </tr> <tr> <td>Masatoshi Seki</td> <td>12/09/2008</td> </tr> </tbody> </table>		Name	Execution Date	Shohei Hata	12/03/2008	Eiji Sakamoto	12/03/2008	Naoki Matsushima	12/04/2008	Hideaki Takemori	12/08/2008	Masatoshi Seki	12/09/2008
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CORRESPONDENCE DATA													
<p>Fax Number: (703)312-6666</p> <p><i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 703-312-6600</p> <p>Email: rperez@antonelli.com</p> <p>Correspondent Name: ANTONELLI, TERRY, STOUT & KRAUS, LLP</p> <p>Address Line 1: 1300 NORTH SEVENTEENTH STREET</p> <p>Address Line 2: SUITE 1800</p> <p>Address Line 4: ARLINGTON, VIRGINIA 22209-3873</p>													
ATTORNEY DOCKET NUMBER:	520.49257X00												

OP \$40.00 12295740

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PATENT
REEL: 022657 FRAME: 0400

NAME OF SUBMITTER:

Alan E. Schiavelli

Total Attachments: 1

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(讓 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi Kyowa Engineering Co., Ltd., a corporation organized under the laws of Japan, located at 10-2, 3-chome, Benten-cho, Hitachi-shi, Ibaraki 317-0072, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi Kyowa Engineering Co., Ltd., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SUBMOUNT AND ITS MANUFACTURING METHOD

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi Kyowa Engineering Co., Ltd., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi Kyowa Engineering Co., Ltd.,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1) Shohei Hata
Shohei HATA

Shohei HATA

Dec. 3, 2008

2) Eiji Sakamoto

Eiji SAKAMOTO

Dec. 3, 2008

3) Naoki Matsushima

Naoki MATSUSHIMA

Dec. 4. 2008

4) Hideaki Takemori

Hideaki TAKEMORI

Dec. 8, 2008

5) Masatoshi Suki

Masatoshi SEKI

Dec. 9, 2008

6) _____

7)

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10)

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